

Remarks

Entry of the amendment presented, reconsideration of the application and allowance of all pending claims are respectfully requested. Claims 1-14 and 30-33 remain pending.

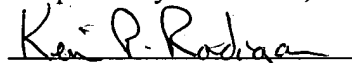
In accordance with 37 C.F.R. 1.121(c)(1)(ii), a marked-up version of the amended claims is provided on one or more pages separate from the amendment. These pages are appended at the end of the Response.

By this paper, claim 1 is again amended to address the 35 U.S.C. §112, second paragraph, rejection of claims 1-14 stated in the final Office Action. This amendment is submitted pursuant to the telephone interview between the Examiner and applicants' undersigned representative on January 23, 2003. Based upon this amendment, withdrawal of the 35 U.S.C. §112, second paragraph, rejection to claims 1-14 is respectfully requested. No new matter is added to the application by any amendment presented herewith.

Substantively, the Examiner's is requested to enter and consider the Remarks contained in applicants' amendment filed January 13, 2003 responsive to the final Office Action. For the reasons stated therein, this application is believed to be in condition for allowance and such action is respectfully requested.

Applicants' undersigned attorney is available should the Examiner wish to discuss this application further.

Respectfully submitted,



Kevin P. Radigan, Esq.

Attorney for Applicants

Registration No. 31,789

Dated: January 23, 2003

HESLIN ROTHENBERG FARLEY & MESITI P.C.

5 Columbia Circle

Albany, New York 12203

Telephone: (518) 452-5600

Facsimile: (518) 452-5579

BUR919990304US1

Marked-Up Version of Claims

In the Claims:

Please amend claim 1 as follows:

1. (Thrice Amended) A structure comprising:

a first substrate and a second substrate; and

first solder bumps and second solder bumps offset therebetween, wherein said first solder bumps and said second solder bumps are separate [sets of] solder bumps disposed between said first substrate and said second substrate, and wherein said second solder bumps have at least a portion that melts at a lower temperature than said first solder bumps.